

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-5. (Canceled without prejudice or disclaimer).

6. (Previously Presented) A circuit board comprising:

an insulator plate;

a conductor layer bonded to a surface of the insulator plate;

a dielectric layer provided in a gap portion between the insulator plate and the conductor layer wherein:

the following relationship exists among the dielectric constant of the dielectric layer ϵ_g , the dielectric constant of the insulator plate ϵ_b , the thickness of the gap portion L_g , and the thickness of the insulator plate L_b ,

$$\epsilon_g \geq \epsilon_b \times (L_g/L_b).$$